Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

CHO-BOND® 4660 and 4669

ONE COMPONENT FLEXIBLE ELECTRICALLY CONDUCTIVE POLYISOBUTYLENE SEALANT

Customer Value Proposition:

CHO-BOND 4660 is a silver-plated copper filled, one-component conductive polyisobutylene. It is designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Its non-hardening characteristic makes it particularly suited for shielding joints and seams which are likely to be disassembled or applications where vibration and thermal shock resilience is required. Minimum recommended bond line for CHO-BOND 4660 is 0.015 inches (0.18 mm). CHO-BOND 4660 dries to touch in minutes and develops its final material properties in 168 hours. The compound remains permanently flexible and adherent with no tendency to crack or pull away from the substrate. Some surface crusting may be experienced, but CHO-BOND 4660 will remain pliable below the surface. In addition, CHO-BOND 4660 may be used to help seal against gases as the polyisobutlyene polymer system has excellent impermeability properties.

Parker Chomerics also offers an extended working life version of CHO-BOND 4660 called CHO-BOND 4669. CHO-BOND 4669 will exhibit the same final properties as CHO-BOND 4660 but has an extended, 2 hour working life. Typical applications include access panels, shielded room joints, temporary military shelters, hardware, bulkhead feed through fittings, and building conduits.

Features and Benefits:

• One component	• Easy to use, no weighing or mixing required.
• Silver plated copper filler	• Good conductivity 0.080 ohm-cm
• Polyisobutylene binder	• 30 minute working life, 168 hrs for final properties to develop, remains flexible, No corrosive by-products generated during drying to damage substrate, excellent impermeability to gases. Primerless system.
• Light weight	• More coverage per gram of material, minimal weight added to assembly or vehicle.
• Gritty paste	• Easy to dispense with standard caulking gun. CHO-BOND 4660 can be used on overhead or vertical surfaces.
• Extended working life version: CHO-BOND 4669	• 2 hr working life, 168 hrs for final properties to develop, slower evaporating solvent system.

Contact Information:

Parker Hannifin Corporation
Chomerics Division
77 Dragon Court
Woburn, MA 01801

phone 781 935 4850
fax 781 933 4318
chomailbox@parker.com

www.chomerics.com
www.parker.com/chomerics

Parker Chomerics

ENGINEERING YOUR SUCCESS.

CHO-BOND 4660 and 4669 Conductive Caulk - Product Information

Table 1 Typical Properties

Typical Properties	Typical Values		Test Method	
	CHO-BOND 4660	CHO-BOND 4669		
Polymer	Polyisobutylene		N/A	
Filler	Silver-Plated Copper		N/A	
Mix Ratio, A : B (by weight)	1-part		N/A	
Color	Black	Gray	N/A	(Q)
Consistency	Gritty Paste		N/A	(Q)
Maximum DC Volume Resistivity	0.080 ohm-cm		CHO-95-40-5555*	(Q/C)
Minimum Lap Shear Strength	N/A		CHO-95-40-5300*	
Minimum Peel Strength	N/A		CHO-95-40-5302*	
Wet Density	2.0 g/ml		ASTM D792	(Q/C)
Hardness	N/A		ASTM-D2240	
Continuous Use Temperature	- 55°C to 100°C (-67 °F to 212 °F)		N/A	(Q)
Elevated Temperature Cure Cycle	None		N/A	
Room Temperature Cure	1 week**		N/A	(Q)
Working Life	0.5 hour	2.0 hours	N/A	(Q)
Shelf Life, unopened	6 months @ 25°C (77°F)		N/A	(Q)
Minimum thickness recommended	0.015 in (0.18 mm)		N/A	
Maximum thickness recommended	0.125 in (3.18 mm)		N/A	
Volatile Organic Content (VOC)	305 g/l	340 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	1375 in^2 (8871 cm^2)		N/A	
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	90 feet (27.4 m)		N/A	

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.
** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours).

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 4660	113.4	2 fluid ounce aluminum foil tube	51-02-4660-0000	Not Required
	681	0.1 gallon fiber cartridge	51-05-4660-0000	Not Required
CHO-BOND 4669	113.4	2 fluid ounce aluminum foil tube	51-02-4669-0000	Not Required
	681	0.1 gallon fiber cartridge	51-05-4669-0000	Not Required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

www.chomerics.com
www.parker.com/chomerics

Parker Chomerics

ENGINEERING YOUR SUCCESS.